

Abstract of the Disclosure:

A carrier has a metal area that is essentially composed of copper. A chip has a rear side metallization layer. A buffer layer, essentially composed of nickel and having a thickness of between 5 μm and 10 μm , is arranged on the metal area. The chip does not have a chip housing and is arranged on the metal area, which has been provided with the buffer layer, such that only one connecting medium is arranged between the rear side metallization layer of the chip and the buffer layer.

MPW/tk